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**Semiconductor devices –
Part 16-3: Microwave integrated circuits – Frequency converters**

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

SEMICONDUCTOR DEVICES –

Part 16-3: Microwave integrated circuits –
Frequency converters

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This Consolidated version of IEC 60747-16-3 bears the edition number 1.2. It consists of the first edition (2002-05) [documents 47E/212/FDIS and 47E/219/RVD], its amendment 1 (2009-03) [documents 47E/357/CDV and 47E/372/RVC] and its amendment 2 (2017-08) [documents 47E/545/CDV and 47E/562/RVC]. The technical content is identical to the base edition and its amendments.

In this Redline version, a vertical line in the margin shows where the technical content is modified by amendments 1 and 2. Additions are in green text, deletions are in strikethrough red text. A separate Final version with all changes accepted is available in this publication.

International Standard IEC 60747-16-3 has been prepared by subcommittee 47E: Discrete semiconductor devices, of IEC technical committee 47: Semiconductor devices.

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SEMICONDUCTOR DEVICES –

Part 16-3: Microwave integrated circuits – Frequency converters

1 Scope

This part of IEC 60747 provides new measuring methods, terminology and letter symbols, as well as essential ratings and characteristics for integrated circuit microwave frequency converters.

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

~~IEC 60050-702:1992, International Electrotechnical Vocabulary – Chapter 702: Oscillations, signals and related devices~~

~~IEC 60617-12, Graphical symbols for diagrams – Part 12: Binary logic elements~~

~~IEC 60617-13, Graphical symbols for diagrams – Part 13: Analogue elements~~

~~IEC 60747-1:1983, Semiconductor devices – Discrete devices and integrated circuits – Part 1: General~~

~~IEC 60747-16-1:2001, Semiconductor devices – Part 16-1: Microwave integrated circuits – Amplifiers –
Amendment 1 (2007)⁴~~

IEC 60050-702, International Electrotechnical Vocabulary – Chapter 702: Oscillations, signals and related devices (available at < <http://www.electropedia.org/> >)

IEC 60617, Graphical symbols for diagrams (available at < <http://std.iec.ch/iec60617> >)

IEC 60747-1:2006, Semiconductor devices – Part 1: General
IEC 60747-1:2006/AMD 1:2010

IEC 60748-2:1997, Semiconductor devices – Integrated circuits – Part 2: Digital integrated circuits

IEC 60748-3, Semiconductor devices – Integrated circuits – Part 3: Analogue integrated circuits

IEC 60748-4, Semiconductor devices – Integrated circuits – Part 4: Interface integrated circuits

⁴ ~~There exists a consolidated edition 1.1 published in 2007, including the base publication (2001) and its Amendment 1 (2007).~~

IEC 61340-5-1:2007, *Electrostatics – Part 5-1: Protection of electronic devices from electrostatic phenomena – General requirements*

IEC/TR 61340-5-2:2007, *Electrostatics – Part 5-2: Protection of electronic devices from electrostatic phenomena – User guide*

FINAL VERSION

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